

# PSMN1R0-40ULD

N-channel 40 V, 1.1 m $\Omega$ , 280 A logic level MOSFET in SOT1023A enhanced package for UL2595, using NextPower-S3 Schottky-Plus technology

23 May 2018

Product data sheet

### 1. General description

SOT1023A with improved creepage and clearance to meet UL2595 requirements 280 Amp, logic level gate drive N-channel enhancement mode MOSFET in 150 °C LFPAK56 package using advanced TrenchMOS Superjunction technology. This product has been designed and qualified for high performance power switching applications.

### 2. Features and benefits

- Improved creepage and clearance meets the requirements of UL2595
- 280 A capability
- Avalanche rated, 100% tested at I<sub>AS</sub> = 190 A
- NextPower-S3 technology delivers 'superfast switching with soft recovery'
- Low Q<sub>RR</sub>, Q<sub>G</sub> and Q<sub>GD</sub> for high system efficiency and low EMI designs
- Schottky-Plus body-diode, gives soft switching without the associated high I<sub>DSS</sub> leakage
- Optimised for 4.5 V gate drive utilising NextPower-S3 Superjunction technology
- High reliability LFPAK (Power SO8) package, copper-clip, solder die attach and qualified to 150 °C
- Exposed leads can be wave soldered, visual solder joint inspection and high quality solder joints
- Low parasitic inductance and resistance

# 3. Applications

- · Brushed and brushless motor control
- Battery powered appliances where enhanced creepage and clearance is required to meet UL2595
- For non-UL2595 applications please use PSMN1R0-40YLD

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
$V_{DS}$	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 150 °C		-	-	40	V	
I <sub>D</sub>	drain current	V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>	[1]	-	-	280	Α	
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	-	164	W	
Tj	junction temperature			-55	-	150	°C	
Static characte	Static characteristics							
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C; Fig. 10; Fig. 11		-	1.1	1.4	mΩ	
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C; Fig. 10; Fig. 11		-	0.93	1.1	mΩ	



Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Dynamic characteristics							
$Q_{GD}$	gate-drain charge	I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 4.5 V;		-	17	-	nC
Q <sub>G(tot)</sub>	total gate charge	Fig. 12; Fig. 13		-	59	-	nC

<sup>[1] 280</sup>A continuous current has been successfully demonstrated during application tests. Practically, the current will be limited by PCB, thermal design and operating temperature.

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		D
2	S	source		
3	S	source		G—CFA
4	G	gate	7	mbb076 S
mb	D	mounting base; connected to drain	1 2 3 4 sot1023a_sv LFPAK56-UL2595 (SOT1023A)	

# 6. Ordering information

### **Table 3. Ordering information**

Type number Package					
	Name	Description	Version		
PSMN1R0-40ULD	LFPAK56-UL 2595	plastic, single-ended surface-mounted package (LFPAK56); 4 leads; 1.27 mm pitch	SOT1023A		

## 7. Marking

### Table 4. Marking codes

Type number	Marking code
PSMN1R0-40ULD	ID04UL

# 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 150 °C		-	40	V
$V_{DSM}$	peak drain-source voltage	$t_p \le 20 \text{ ns}; f \le 500 \text{ kHz}; E_{DS(AL)} \le 200 \text{ nJ};$ pulsed		-	45	V
$V_{DGR}$	drain-gate voltage	25 °C ≤ $T_j$ ≤ 150 °C; $R_{GS}$ = 20 kΩ		-	40	V
V <sub>GS</sub>	gate-source voltage			-20	20	V
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	164	W
I <sub>D</sub>	drain current	V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>	[1]	-	280	Α
		V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 100 °C; <u>Fig. 2</u>		-	198	Α
I <sub>DM</sub>	peak drain current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 \text{ °C}$ ; Fig. 3		-	1168	Α
T <sub>stg</sub>	storage temperature			-55	150	°C
T <sub>j</sub>	junction temperature			-55	150	°C
T <sub>sld(M)</sub>	peak soldering temperature			-	260	°C
V <sub>ESD</sub>	electrostatic discharge voltage	НВМ		2	-	kV
Source-drain	n diode					'
Is	source current	T <sub>mb</sub> = 25 °C		-	165	Α
I <sub>SM</sub>	peak source current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 \degree C$		-	1284	Α
Avalanche ru	uggedness					•
E <sub>DS(AL)S</sub>	non-repetitive drain- source avalanche energy	$I_D$ = 85 A; $V_{sup} \le 40$ V; $R_{GS}$ = 50 Ω; $V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; unclamped; $t_p$ = 0.26 ms	[2]	-	570	mJ
		$I_D$ = 25 A; $V_{sup} \le 40$ V; $R_{GS}$ = 50 Ω; $V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; unclamped; $t_p$ = 3.8 ms	[2]	-	2328	mJ
I <sub>AS</sub>	non-repetitive avalanche current	$V_{sup} \le 40 \text{ V}; V_{GS} = 10 \text{ V}; T_{j(init)} = 25 \text{ °C};$ $R_{GS} = 50 \Omega$	[2]	-	190	А

<sup>[1] 280</sup>A continuous current has been successfully demonstrated during application tests. Practically, the current will be limited by PCB, thermal design and operating temperature.

<sup>[2]</sup> Protected by 100% test.

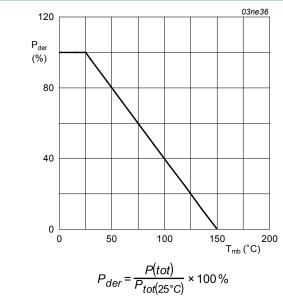
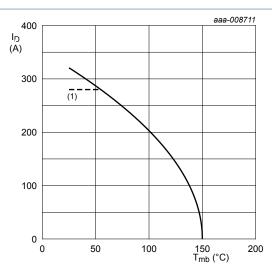


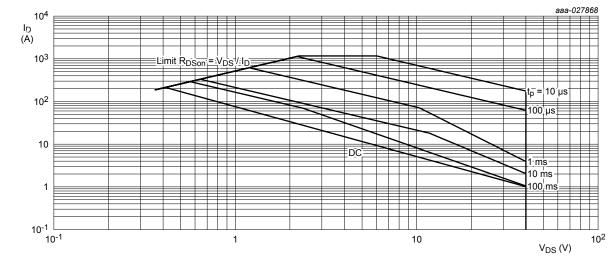
Fig. 1. Normalized total power dissipation as a function of mounting base temperature



(1) 280A continuous current has been successfully demonstrated during applications tests. Practically, the current will be limited by PCB, thermal design and operating temperature.

V<sub>GS</sub>≥10V

Fig. 2. Continuous drain current as a function of mounting base temperature



 $T_{mb}$  = 25 °C;  $I_{DM}$  is a single pulse

Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 4	-	0.66	0.76	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	Fig. 5 Fig. 6	-	50 125	-	K/W K/W

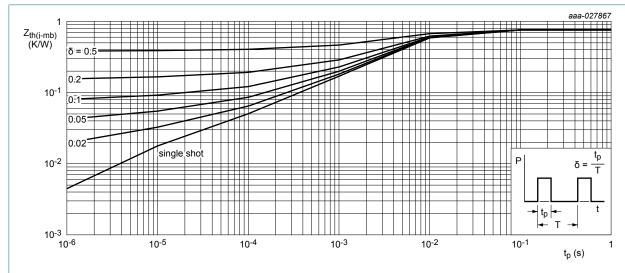


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

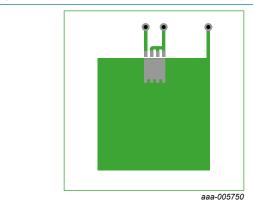


Fig. 5. PCB layout for thermal resistance junction to ambient 1" square pad; FR4 Board; 2oz copper

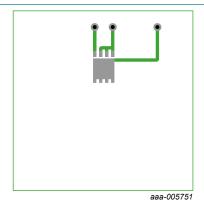


Fig. 6. PCB layout for thermal resistance junction to ambient minimum footprint; FR4 Board; 2oz copper

### 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static charac	teristics					
V <sub>(BR)DSS</sub>	drain-source	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>i</sub> = 25 °C	40	-	-	V
	breakdown voltage	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = -55 °C	$i_1 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_2 = 0 \text{ V}; T_j = -55 \text{ °C}$ $i_3 = 0 \text{ V}; T_j = -55 \text{ °C}$ $i_4 = 0 \text{ V}; T_j = -55 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 125 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C}$ $i_5 = 0 \text{ V}; T_j = 25 \text{ °C};$ $i_5 = 0 \text{ V}; $	V		
V <sub>GS(th)</sub>	gate-source threshold voltage	I <sub>D</sub> = 1 mA; V <sub>DS</sub> =V <sub>GS</sub> ; T <sub>j</sub> = 25 °C	1.05	1.7	2.2	V
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	25 °C ≤ T <sub>j</sub> ≤ 150 °C	-	-5.1	-	mV/K
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = 32 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	1	μΑ
		V <sub>DS</sub> = 32 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 125 °C	-	9	-	μΑ
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 16 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	- 2.2 - 100 100 1.1 1.93 1.4 2.45 	nA
		V <sub>GS</sub> = -16 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	100	nA
$R_{DSon}$	drain-source on-state resistance	V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C; Fig. 10; Fig. 11	-	0.93	1.1	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 150 °C; Fig. 10; Fig. 11	-	-	1.93	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C; Fig. 10; Fig. 11	-	1.1	1.4	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 150 °C; Fig. 10; Fig. 11	-	-	2.45	mΩ
$R_G$	gate resistance	f = 1 MHz	-	1.3	-	Ω
Dynamic cha	racteristics				•	'
Q <sub>G(tot)</sub>	total gate charge	I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 10 V; Fig. 12; Fig. 13	-	127	-	nC
		I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 4.5 V; Fig. 12; Fig. 13	-	59	-	nC
		I <sub>D</sub> = 0 A; V <sub>DS</sub> = 0 V; V <sub>GS</sub> = 10 V	-	115	-	nC
Q <sub>GS</sub>	gate-source charge	I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 4.5 V;	-	19	-	nC
Q <sub>GS(th)</sub>	pre-threshold gate- source charge	Fig. 12; Fig. 13	-	12	-	nC
Q <sub>GS(th-pl)</sub>	post-threshold gate- source charge		-	8	-	nC
$Q_{GD}$	gate-drain charge	1	-	17	-	nC
V <sub>GS(pl)</sub>	gate-source plateau voltage	I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; <u>Fig. 12</u> ; <u>Fig. 13</u>	-	2.7	-	V
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 0 V; f = 1 MHz;	-	8845	-	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C; <u>Fig. 14</u>	-	1878	-	pF
C <sub>rss</sub>	reverse transfer capacitance		-	382	-	pF
	capacitarios	The state of the s	1	1	1	1

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
t <sub>d(on)</sub>	turn-on delay time	$V_{DS} = 20 \text{ V}; R_L = 0.8 \Omega; V_{GS} = 4.5 \text{ V};$		-	52	-	ns
t <sub>r</sub>	rise time	$V_{DS} = 20 \text{ V}; R_L = 0.8 \Omega; V_{GS} = 4.5 \text{ V};$ $R_{G(ext)} = 5 \Omega$ $V_{GS} = 0 \text{ V}; V_{DS} = 20 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ °C}$ $I_S = 25 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}; Fig. 15$ $I_S = 25 \text{ A}; dI_S/dt = -100 \text{ A/μs}; V_{GS} = 0 \text{ V};$ $V_{DS} = 20 \text{ V}; Fig. 16$		-	62	-	ns
t <sub>d(off)</sub>	turn-off delay time			-	65	-	ns
t <sub>f</sub>	fall time			-	38	-	ns
Q <sub>oss</sub>	output charge			-	51	-	nC
Source-dra	in diode					•	
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = 25 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C; <u>Fig. 15</u>		-	0.78	1.2	V
t <sub>rr</sub>	reverse recovery time			-	48	-	ns
Q <sub>r</sub>	recovered charge	V <sub>DS</sub> = 20 V; <u>Fig. 16</u>	[1]	-	67	-	nC
t <sub>a</sub>	reverse recovery rise time			-	28.6	-	ns
t <sub>b</sub>	reverse recovery fall time			-	23.8	-	ns

### [1] includes capacitive recovery

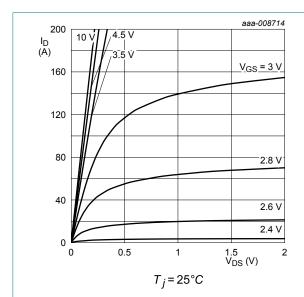


Fig. 7. Output characteristics; drain current as a function of drain-source voltage; typical values

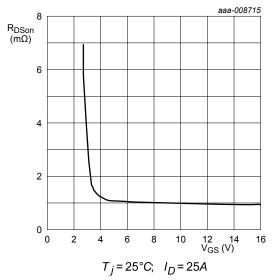


Fig. 8. Drain-source on-state resistance as a function of gate-source voltage; typical values

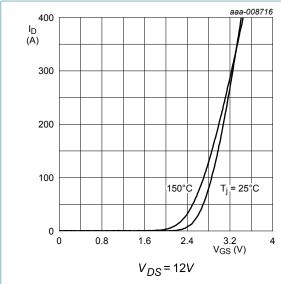


Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

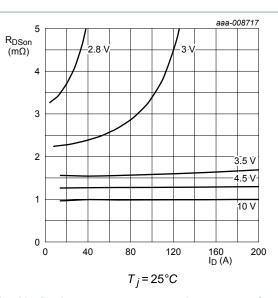


Fig. 10. Drain-source on-state resistance as a function of drain current; typical values

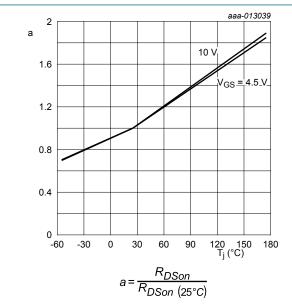


Fig. 11. Normalized drain-source on-state resistance factor as a function of junction temperature

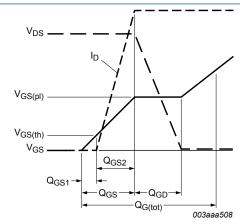


Fig. 12. Gate charge waveform definitions

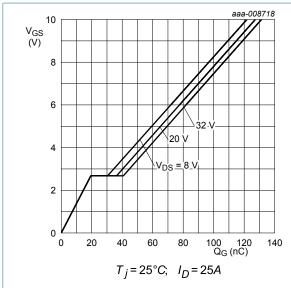


Fig. 13. Gate-source voltage as a function of gate charge; typical values

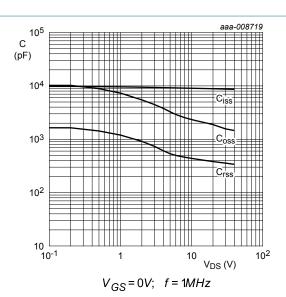


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

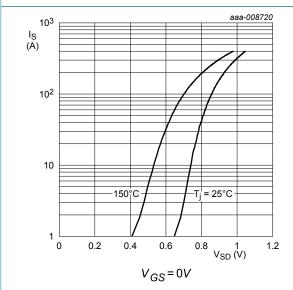


Fig. 15. Source current as a function of source-drain voltage; typical values

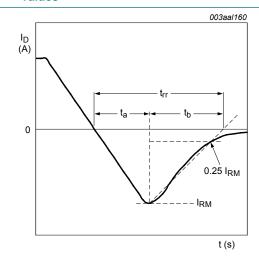
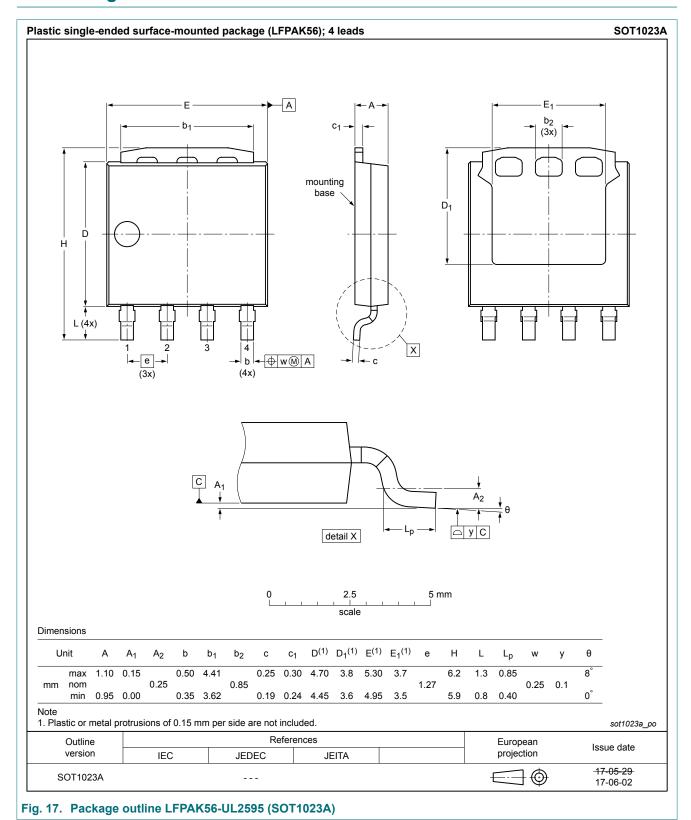


Fig. 16. Reverse recovery timing definition

# 11. Package outline



# 12. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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### **Contents**

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Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

### Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибьютором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «JONHON», а так же официальным дистрибьютором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «FORSTAR».



**«JONHON»** (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«**FORSTAR**» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



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